

PART INFORMATION		
Mfg Item Number		T1023NXN7MQA
Mfg Item Name		FCPBGA 19X19 525 1.92
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2017-04-03
Response Document ID		00HWK50008S289A1.1
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
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Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
Representative Phone		512-895-3406
Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		Yes
Pb Free		Yes
HalogenFree		Yes
Plating Indicator		e1
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number		T1023NXN7MQA
Mfg Item Name		FCPBGA 19X19 525 1.92
Version		ALL
Weight		0.955400
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		3
Peak Processing Temperature		260 C
Max Time at Peak Temperature		40 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Solder Balls - Lead Free	0.1303						g					
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00065267	g	5009	0.5009		683	0.0683
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.00391604	g	30054	3.0054		4098	0.4098
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.12573129	g	964937	96.4937		131600	13.16
Underfill	0.0056						g					
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1		0.000028	g	5000	0.5		29	0.0029
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.000028	g	5000	0.5		29	0.0029
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.00084	g	150000	15		879	0.0879
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00056	g	100000	10		586	0.0586
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000028	g	5000	0.5		29	0.0029
Underfill		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.000168	g	30000	3		175	0.0175
Underfill		Glass	Silica, vitreous	60676-86-0		0.00336	g	600000	60		3518	0.3518
Underfill		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.000028	g	5000	0.5		29	0.0029
Underfill		Solvents, additives, and other materials	Proprietary Material-Other aliphatic amine compounds	-		0.00056	g	100000	10		586	0.0586
Organic Substrate, Halogen-free	0.7663						g					
Organic Substrate, Halogen-free		Arsenic/Arsenic Compounds	Arsenic	7440-39-2		0.0000069	g	9	0.0009		7	0.0007
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.00451351	g	5890	0.589		4724	0.4724
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.35934413	g	468934	46.8934		376131	37.6131
Organic Substrate, Halogen-free		Plastics/polymers	2,2'-(1,1-methylethyldene)bis(4,1-phenyleneoxymethylene)bisoxirane	1675-54-3		0.00096937	g	1265	0.1265		1014	0.1014
Organic Substrate, Halogen-free		Plastics/polymers	Other Epoxy resins	-		0.06904746	g	90105	9.0105		72270	7.227
Organic Substrate, Halogen-free		Lead/Lead Compounds	Lead	7439-92-1		0.00000383	g	5	0.0005		4	0.0004
Organic Substrate, Halogen-free		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.01527849	g	19938	1.9938		15991	1.5991
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.16421962	g	214302	21.4302		171885	17.1885
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.09921813	g	77278	7.7278		61982	6.1982
Organic Substrate, Halogen-free		Metals	Silver, metal	7440-22-4		0.00024215	g	316	0.0316		253	0.0253
Organic Substrate, Halogen-free		Metals	Tin, metal	7440-31-5		0.0077925	g	10169	1.0169		8156	0.8156
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-51-2		0.08494129	g	110846	11.0846		88906	8.8906
Organic Substrate, Halogen-free		Metals	Copper phthalocyanine	147-14-8		0.00072252	g	943	0.0943		756	0.0756
Pb-free Bumped Semiconductor D	0.0532						g					
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.000266	g	5000	0.5		278	0.0278
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.00016758	g	3150	0.315		175	0.0175
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00462042	g	86950	8.685		4636	0.4636
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.0004788	g	9000	0.9		501	0.0501
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.0478672	g	896000	89.6		49892	4.9892

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/T1023NXN7MQA_IPC1752_v11.xml

http://www.freescale.com/mcds/T1023NXN7MQA_IPC1752A.xml